DB2S406

Silicon epitaxial planar type

For high speed switching circuits
DB2J406 in SSMini2 type package

■ Features

- Short reverse recovery time t_{rr}
- Small reverse current I_R
- Contributes to miniaturization of sets, reduction of component count.
- Eco-friendly Halogen-free package

■ Packaging

DB2S40600L Embossed type (Thermo-compression sealing): 3000 pcs / reel (standard)

■ Package

- Code
  SSMini2-F5-B
  Package dimension clicks here.→ Click!
- Pin Name
  1: Cathode
  2: Anode

■ Marking Symbol: 4Q

■ Absolute Maximum Ratings $T_a = 25°C$

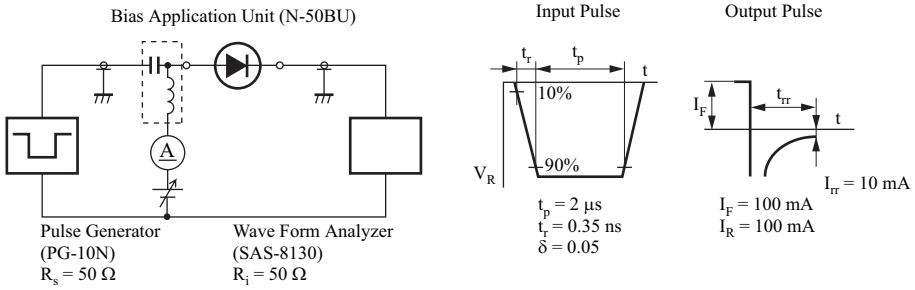
Parameter	Symbol	Rating	Unit
Reverse voltage	V_R	40	V
Repetitive peak reverse voltage	V_{RRM}	40	V
Forward current (Average)	$I_{F(AV)}$	100	mA
Peak forward current	I_{FM}	300	mA
Non-repetitive peak forward surge current *	I_{FSM}	1	A
Junction temperature	T_j	125	°C
Storage temperature	T_{stg}	−55 to +125	°C

Note) *: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

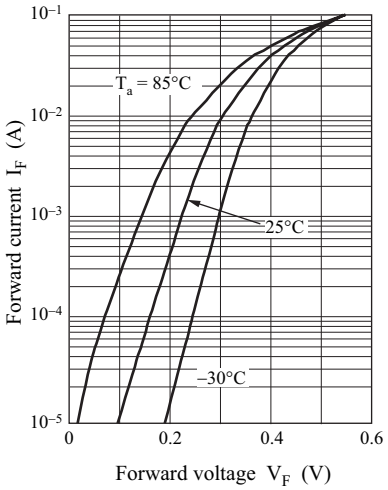
■ Electrical Characteristics $T_a = 25°C \pm 3°C$

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	$I_F = 100$ mA			0.6	V
Reverse current	I_R	$V_R = 40$ V			5	μA
Terminal capacitance	C_t	$V_R = 10$ V, f = 1 MHz		2.2		pF
Reverse recovery time *	t_{rr}	$I_F = I_R = 100$ mA, $I_{rr} = 10$ mA		0.9		ns

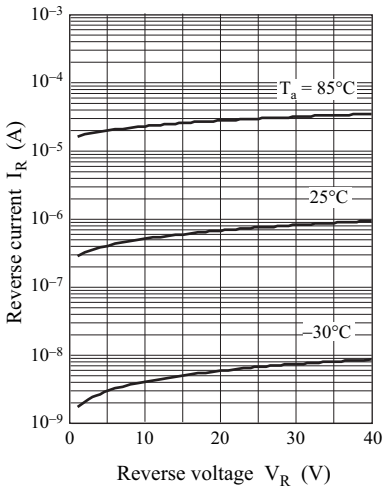
Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.
2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.
3. Absolute frequency of input and output is 250 MHz
*: t_{rr} measurement circuit



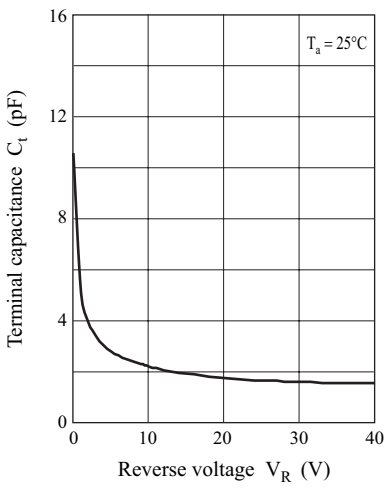
I_F — V_F



I_R — V_R



C_t — V_R



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